

# Application Note

**Hyposaturation type Surface Molding Series Regulator IC**

**SI-3000LU Series**

*Not Recommended for New Designs*

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SANKEN ELECTRIC CO., LTD.

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## 1. General Information

The SI-3000LU is a series regulator IC using a hyposaturation type PNP bipolar transistor in the power section and it can be used with the low difference of input/output voltages. It is provided with an ON / OFF terminal which operates in Active High mode and the current consumption of circuits at OFF time is zero. It is a regulator which can use low ESR capacitors such as ceramic capacitors for the output capacitor at the voltage of 18V.

### ● 1-1 Features

- Output current 250mA  
Output current is 250mA at maximum with the outline of SOT89-5.
- Hyposaturation ( $V_{dif} = 0.5V_{max} / I_o = 0.25A$ )  
It can be designed with low difference of input/output voltages.
- ON/OFF function  
The ON/OFF terminal which can be directly controlled by TTL logic signals is provided.
- Low current consumption  
Current consumption of circuits at OFF time is zero.  
Dark currents at no load are 150 $\mu$ A at maximum.
- Built-in Overcurrent protection / Thermal shutdown  
The current limiting type overcurrent protection and Thermal shutdown circuits are built-in.  
(Automatic restoration type)

### ● 1-2 Application

For on-board local power supplies, power supplies for OA equipment, stabilization of secondary output voltage of regulator and power supply for communication equipment

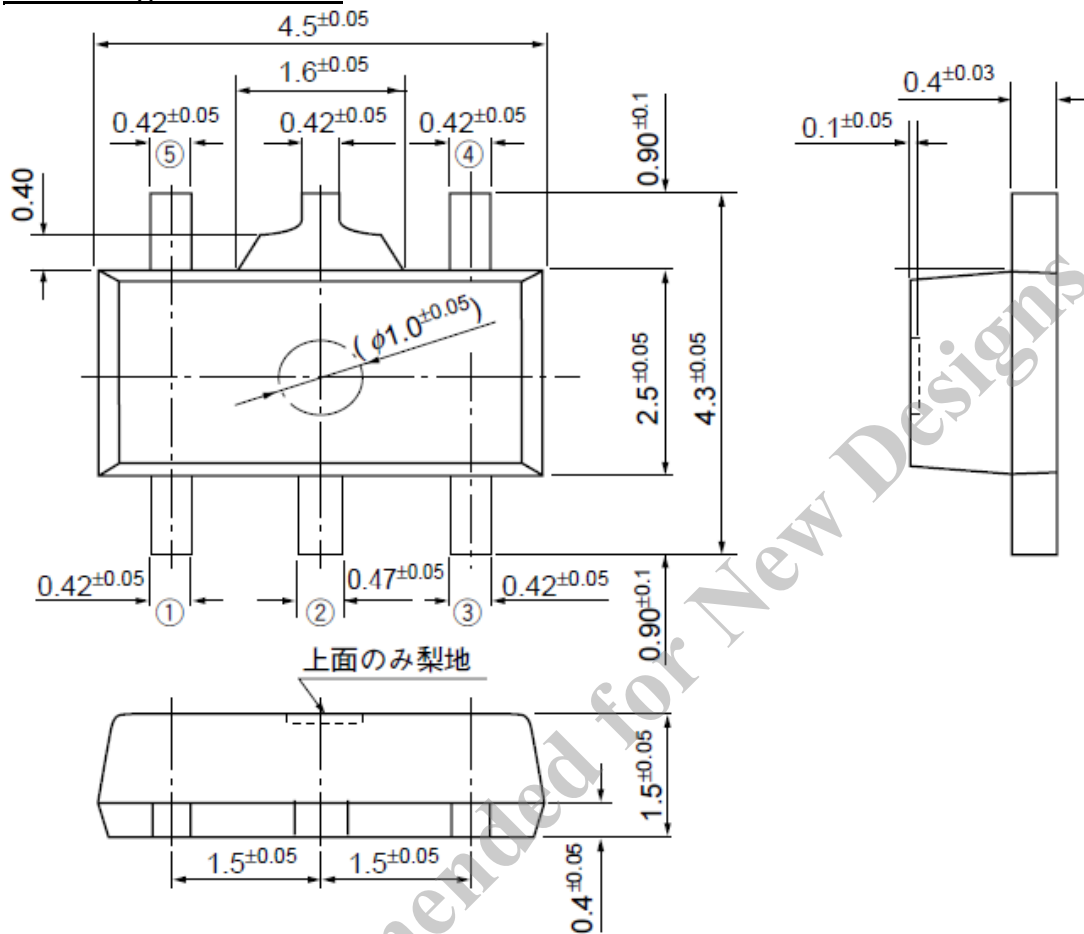
### ● 1-3 Type

- Type: Semiconductor integrated circuits (monolithic IC)
- Structure: Resin molding type (transfer molding)

## 2. Specification

Unit: mm

### ● 2-1 Package Information



Pin assignment

1. ADJ
2. GND
3. V<sub>c</sub>
4. V<sub>IN</sub>
5. V<sub>o</sub>

Resin sealed type

Non-combustibility: UL standards 94V-0

Product mass: about 0.05 g

## ● 2-2 Ratings

### 2-2-1 Absolute Maximum Ratings

 $T_a = 25^\circ\text{C}$ 

Parameter	Symbol	Ratings	Unit
DC Input Voltage	$V_{IN}$	18	V
Output control terminal voltage	$V_c$	$V_{IN}$	V
DC Output Current	$I_o$	250	mA
Power Dissipation	$P_D^{*1}$	0.75	W
Junction Temperature	$T_j^{*2}$	-40 to +135	$^\circ\text{C}$
Storage Temperature	$T_{stg}^{*2}$	-40 to +125	$^\circ\text{C}$
Thermal Resistance (Junction to Ambient Air)	$\theta_{ja}^{*1}$	146	$^\circ\text{C/W}$

\*1: When mounted on glass-epoxy board of  $40 \times 40\text{mm}$  (copper laminate area 100%).

\*2: Thermal protection circuits may operate if the junction temperature exceeds  $135^\circ\text{C}$ .

### 2-2-2 Recommended Conditions

Parameter	Symbol	Ratings		Unit
		min.	max.	
Input Voltage	$V_{in}$	$V_o+2^2$	$V_o+2^2$	V
DC Output Current	$I_o$	0	250	mA
Operating Ambient Temperature	$T_{op}$	-30	85	$^\circ\text{C}$

\*1:  $V_{IN}$  (max) and  $I_o$  (max) are restricted by the relation  $PD = (V_{IN} - V_o) \times I_o$ .

\*2: Refer to the Dropout Voltage parameter.

\*3: For the SI-3012LU, set the input voltage to  $V_{IN} \geq 2.4\text{V}$ , and secure the minimum voltage as explained in "Setting DC Input Voltage" section in Linear Regulator Application Note.

### 2-2-3 Electrical Characteristics

 $T_a = 25^\circ\text{C}$ 

Parameter	Symbol	Ratings			Unit	
		SI-3012LU(Variable)				
		min.	typ.	max.		
Reference Voltage	$V_{ADJ}$	1.210	1.250	1.290	V	
Dropout Voltage	$V_{DIF}$		$V_{IN}=V_o+1\text{V}, I_o=10\text{mA}$	0.3	V	
	Conditions		$I_o=100\text{mA}(V_o=3.3\text{V})$			
	Conditions		$I_o=250\text{mA}(V_o=3.3\text{V})$	0.5		
Line Regulation	$\Delta V_{LINE}$		$V_{IN}=V_o+1$ to $V_o+5\text{V}$ , $I_o=10\text{mA}(V_o=3.3\text{V})$	10	mV	
Load Regulation	$\Delta V_{LOAD}$		$V_{IN}=V_o+1\text{V}$ , $I_o=1$ to $250\text{mA}(V_o=3.3\text{V})$	20	mV	
Temperature Coefficient of Reference Voltage	$\Delta V_o/\Delta T_a$		$\pm 0.3$		$\text{mV}/^\circ\text{C}$	
Ripple Rejection	$R_{REJ}$		55		dB	
	Conditions		$V_{IN}=V_o+1\text{V}$ , $f=100$ to $120\text{Hz}(V_o=3.3\text{V})$			
Quiescent Circuit Current	$I_q$			150	$\mu\text{A}$	
	Conditions		$V_{IN}=V_o+1\text{V}, I_o=0\text{mA}$ $V_c=2\text{V}, R_2=100\text{k}\Omega$			
Circuit Current at Output OFF	$I_q(\text{OFF})$			1	$\mu\text{A}$	
	Conditions		$V_{IN}=V_o+1\text{V}, V_c=0\text{V}$			
Overcurrent Protection Starting Current <sup>*1</sup>	$I_{s1}$	260			mA	
	Conditions		$V_{IN}=V_o+1\text{V}$			
$V_c$ Terminal	Control Voltage (Output ON) <sup>*2</sup>	$V_c, IH$	2.0		V	
	Control Voltage (Output OFF) <sup>*2</sup>	$V_c, IL$		0.8		
	Control Current (Output ON)	$I_c, IH$			40	$\mu\text{A}$
		Conditions		$V_c=2\text{V}$		
	Control Current (Output OFF)	$I_c, IL$		0	-5	$\mu\text{A}$
Conditions			$V_c=0\text{V}$			

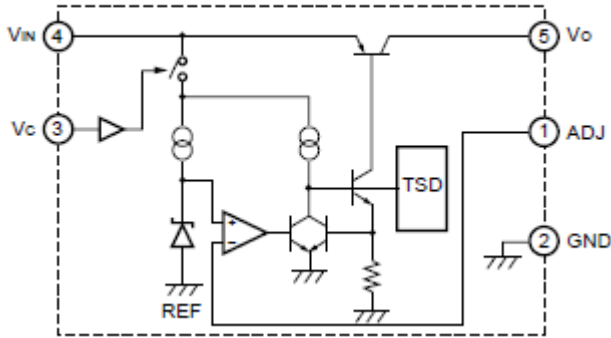
\*1:  $I_{s1}$  is specified at the 5% drop point of output voltage  $V_o$  on the condition that  $V_{IN} = 3.3\text{V}$ , and  $I_o = 10\text{mA}$ .

\*2: Output is OFF when the output control terminal ( $V_c$  terminal) is open. Each input level is equivalent to LS-TTL level. Therefore, the device can be driven directly by LS-TTLs.

● **2-3 Circuit Diagram**

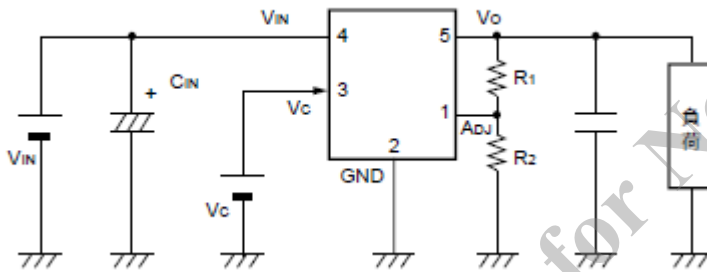
2-3-1 Block Diagram

SI-3012LU



2-3-2 Typical Connection Diagram

SI-3012LU



Co: Output Capacitor (over 10μF)

In the SI-3000LU series, the circuit composition using low ESR capacitors such as ceramic capacitor for the output capacitor is adopted.

C<sub>IN</sub>: Input Capacitor (around 10μF)

R1, R2: resistors for setting output voltages

Output voltages can be adjusted by connecting R1 and R2 as shown in the above figure (Recommended output voltage to be set: 1.5 - 15V).

R2: 100kΩ is recommended.

$$R1 = (Vo - V_{ADJ}) / (V_{ADJ} / R2)$$

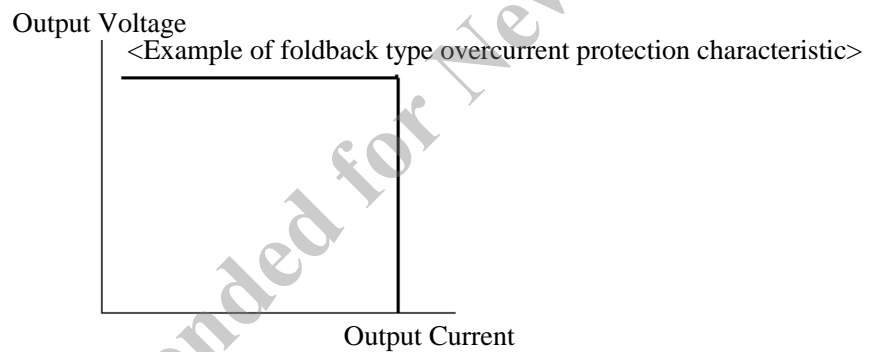
### 3. Operational Description

#### ● 3-1 Voltage Control

In the SI-3000LU series, the driving circuit is controlled by comparing the reference voltage with the ADJ terminal voltage (voltage divided by  $V_o$  detection resistor in fixed output products) to stabilize the output voltage by varying the voltage between the emitter and collector of a main PNP power transistor. The product of voltage between emitter and collector and the output current at this moment is consumed as heat.

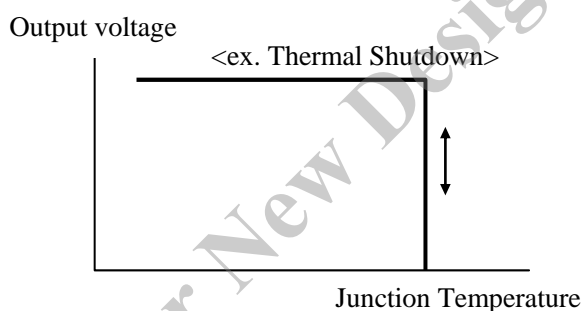
#### ● 3-2 Overcurrent Protection

The current limiting type overcurrent protection function is provided in the SI-3000LU series. In the case of the series regulator, as the output voltage drops subject to the overcurrent protection, the difference of input/output voltages increases to cause significant heating. Special care should be taken for the current limiting type overcurrent protection, since large current flows continuously.



### ● 3-3 Thermal Shutdown

This IC is provided with the overheat protection circuit which detects the semiconductor junction temperature of the IC to limit the driving current, when the junction temperature exceeds the set value (around 150°C). Since the minimum operating temperature of the overheat protection circuit is 130°C, the thermal design of  $T_j < 125^\circ\text{C}$  is required. Since the overheat protection has no hysteresis, as soon as the overload state is released and  $T_j$  falls below the set temperature, the normal operation is automatically restored. When the overheat protection function is operated in the overload state, the output voltage falls, but at the same time the output current is decreased and in the consequence, overheat protection operation and automatic restoration are repeated in a short interval, resulting eventually in the waveforms of output voltage oscillation.



\*Note for thermal shutdown characteristic

This circuit protects the IC against overheat resulting from the instantaneous short circuit, but it should be noted that this function does not assure the operation including reliability in the state that overheat continues due to long time short circuit.



## 4. Cautions

### ● 4-1 External Components

#### 4-1-1 Input Capacitor C<sub>IN</sub>

The input capacitor is required to eliminate noise and stabilize the operation and values of 0.47μF - 10μF are recommended. Any of ceramic capacitors or electrolytic ones may be used for the input capacitor.

#### 4-1-2 Output Capacitor C<sub>O</sub>

In the output capacitor C<sub>O</sub>, larger capacitance than the recommended value is required for phase compensation. Equivalent series resistance values (ESR) of capacitors are limited, and depending on products, therefore the type of recommended capacitors is limited.

- Recommendation: ESR < 0.2Ω (Includes temperature characteristics)

**It is recommended to use ceramic capacitors or functional polymer capacitors.** If electrolytic capacitors having large ESR are used, the phase margin is decreased to cause the possible oscillation of output voltage. Even if oscillation does not occur at low temperature, ESR is increased to cause oscillation, therefore the use of electrolytic capacitors is not recommendable.

#### 4-1-3 Reverse bias protection diode D1

In the case of falling-down of the input voltage, it is recommended to insert a protection diode D1 against the reverse bias between input and output. However, in the case of setting the V<sub>out</sub> < 3.3V or lower, D1 is not required including the case of reverse bias. In order to select a suitable D1, it should be taken into consideration that the diode has adequate forward current withstand voltage against the instantaneous discharge of energy stored in C<sub>out</sub>.

The permissible value of the forward current per unit time of diode is specified in I<sub>FSM</sub> (A) and in the case of our diode, it is specified at 50Hz half wave (10ms), but it should be noted that different companies may specify different times. The selection of diode should be made by converting the specified time into the actual discharging time so as to meet the required I<sub>FSM</sub> (A). The discharging time of C<sub>O</sub> is normally shorter than 1ms, but it is recommended to do the conversion with 1ms in consideration of margin.

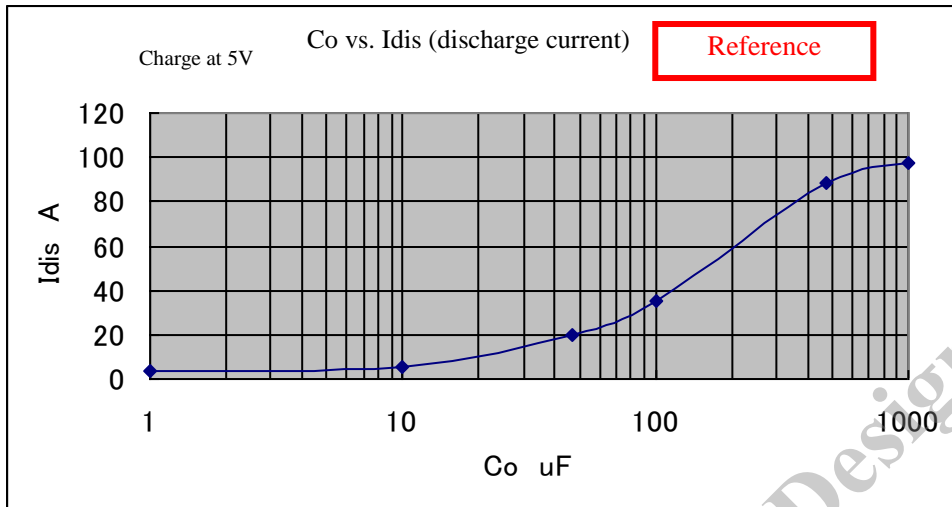
For conversion into I<sub>FSM</sub>, calculation should be made by using the equations (1) and (2).

$$\left(\frac{I_{FSM}}{\sqrt{2}}\right)^2 * t1 = X \quad \text{--- (1) As for } I_{FSM}, \text{ please refer to the catalog of each company.}$$

t1 = specified time in catalog of each company

$$\text{Converted IFSM} = \sqrt{\frac{2 * X}{t2}} \quad \text{--- (2)} \quad t2: \text{ converted time (discharging time of } C_o)$$

<Graph 1>



On the assumption of  $C_{out} = 470\mu\text{F}$ ,  $I_{FSM}$  of around 90A or more (in 1ms time period) is required and according to our specifications of diode,  $I_{FSM}$  is specified for 10ms, therefore the diode of 30A has the tolerated dose of 94.8A (in 1ms) to prove that it is usable.

● **4-2 Pattern Design Notes**

4-2-1 Input / Output Capacitor

The input capacitor C1 and the output capacitor C2 should be connected to the IC as close as possible. If the rectifying capacitor for AC rectifier circuit is on the input side, it can be used as an input capacitor. However, if it is no close to the IC, the input capacitor should be connected in addition to the rectifying capacitor.

4-2-2 ADJ Terminal (Output Voltage Set-up for SI3012LU)

The ADJ terminal is a feedback detection terminal for controlling the output voltage. The output voltage set-up is achieved by connecting R1 and R2.

SI-3012LU: it should be set in a manner that  $I_{ADJ}$  is around  $12.5\mu\text{A}$ .

R1, R2 and output voltage can be obtained by the following equations:

$$I_{ADJ} = V_{ADJ} / R2 \quad \left[ \begin{array}{l} *V_{ADJ} = 1.25V \pm 3\% \text{ (SI-3012LU, } R2 = 100k\Omega \text{ recommended)} \end{array} \right]$$

$$R1 = (V_o - V_{ADJ}) / I_{ADJ} \quad R2 = V_{ADJ} / I_{ADJ}$$

$$V_{out} = R1 \times (V_{ADJ} / R2) + V_{ADJ}$$

## 5. Applications

### ● 5-1 Output ON/OFF Control

The ON/OFF control of output can be made by directly applying voltage to No. 1 Vc terminal. When the Vc terminal is open, the operation is in OFF. The Vc terminal is in OFF below 0.8V and in ON at above 2V.

### ● 5-2 Thermal Design

Calculation of heat dissipation

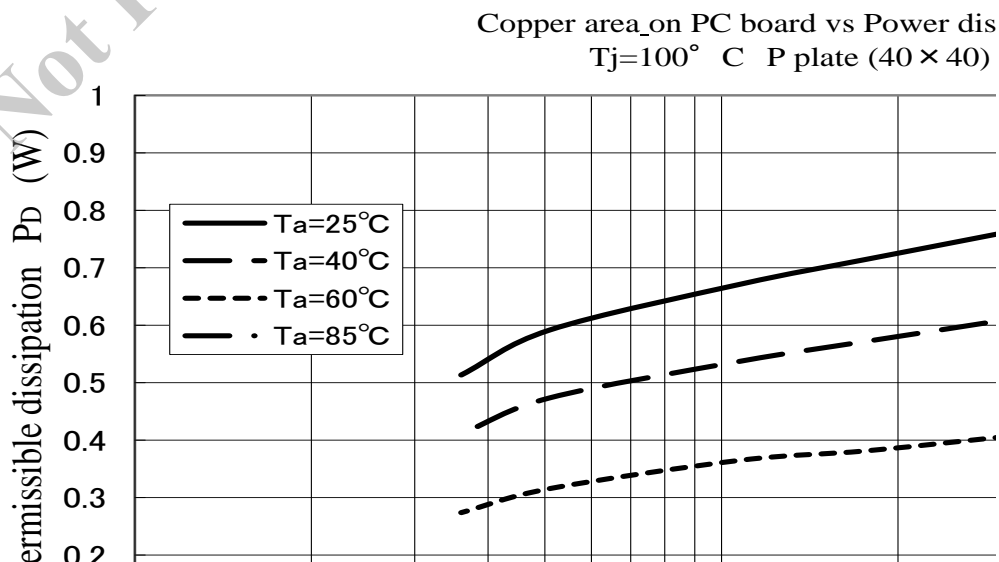
Heat generation of the surface mounting IC is generally dependent on size, material and copper foil area of the mounted printed circuit board. The inner frame stage on which the monolithic IC is mounted is directly connected to the GND terminal (2 pin). Therefore, the heat dissipation effect is increased by enlarging the copper foil area connected to the GND terminal. As shown in Fig. 1, it is recommended to design in a manner that the insulation film is opened only in the solder pattern of Nos. 5, 6, 7 and 8 pins connected to the GND pattern widely arranged.

As the junction temperature  $T_j$  (MAX) is a product-specific value, it must be observed strictly. For this purpose, heat sink design (thermal resistance of board) which is appropriate for  $P_d$  (MAX) and  $T_a$  MAX is required. This is graphically shown in the heat derating curve for easy understanding. The heat dissipation design is done in the following procedure.

- 1) The highest ambient temperature in the set  $T_a$  MAX is obtained.
- 2) The maximum loss  $P_d$ MAX which varies the input/output conditions is obtained.

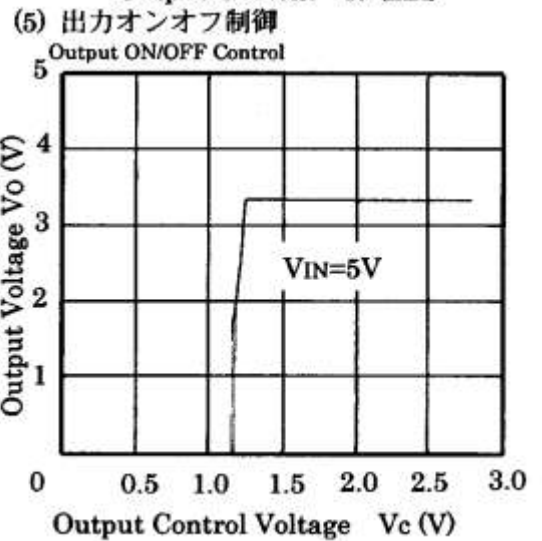
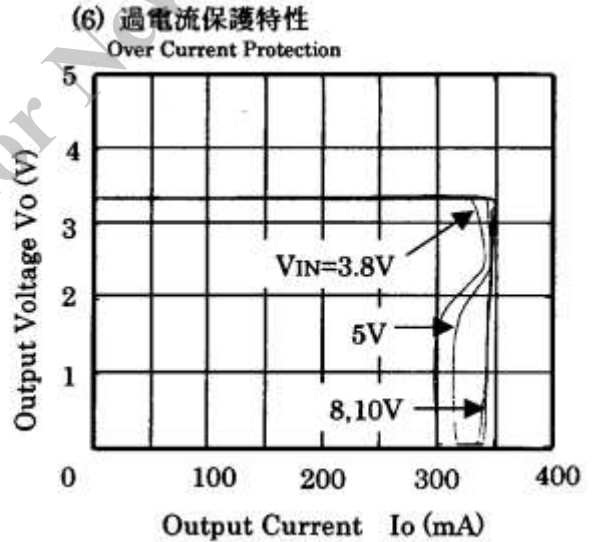
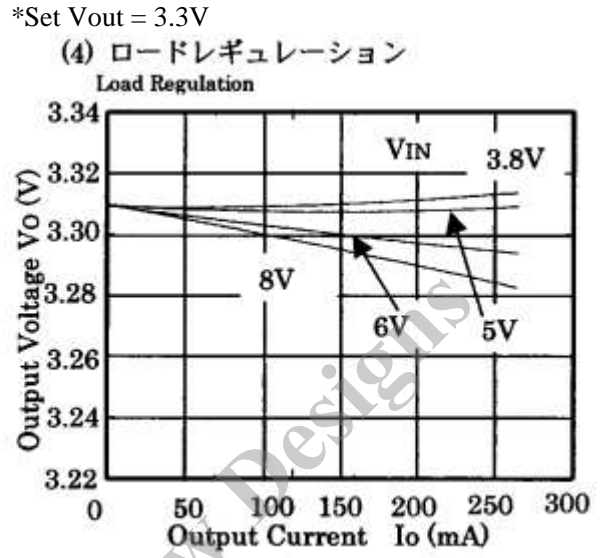
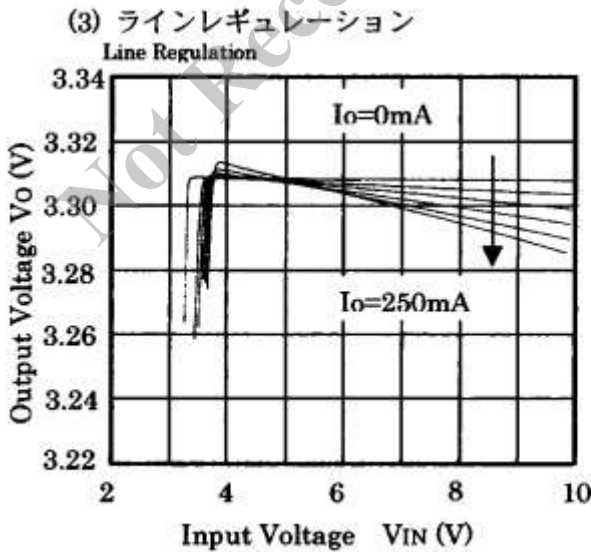
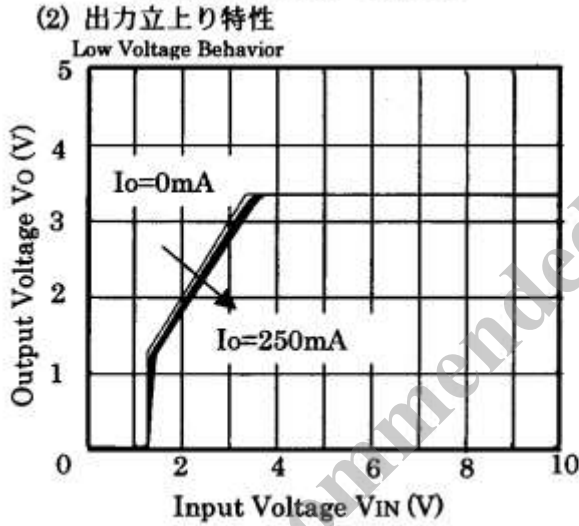
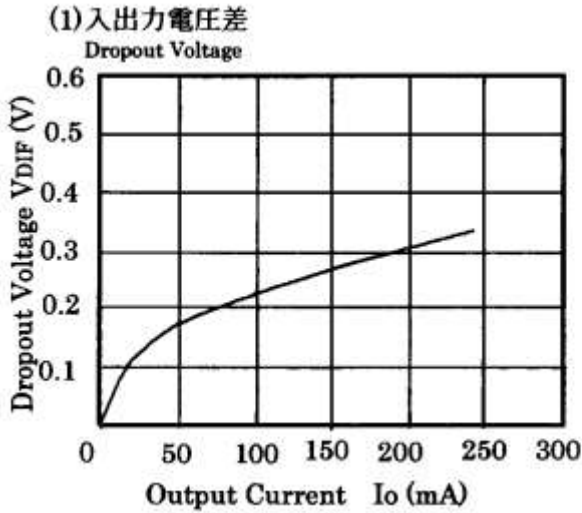
$$P_d = (V_{IN} - V_{out}) \times I_{out}$$

- 3) The area of copper foil is determined from the graph of copper foil area vs. permissible dissipation below shown.



# 6. Typical Characteristics

SI-3012LU (Ta = 25°C)



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